

**COMBINED DECLARATION AND POWER OF ATTORNEY  
FOR PATENT APPLICATION**

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As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a

patent is sought on the invention entitled SEMICONDUCTOR SUBSTRATE, SOI SUBSTRATE AND MANUFACTURING METHOD THEREFOR

\_\_\_\_\_, the specification of which

☐ is attached hereto ☒ was filed on 11/FEB/2002 as United States Appl'n No. or

PCT International Application No. 10/068,988

and was amended on \_\_\_\_\_ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR §1.56.

I hereby claim foreign priority benefits under 35 U.S.C. §119(a)-(d) or §365(b), of any foreign application(s) for patent or inventor's certificate, or §365(a) of any PCT international application which designates at least one country other than the United States, listed below and have also identified below any foreign application for patent or inventor's certificate, or PCT international application having a filing date before that of the application on which priority is claimed:

<u>Country</u>	<u>Application No.</u>	<u>Filed(Day/Mo./Yr.)</u>	<u>Priority Claimed (Yes/No)</u>
Japan	033808/2001(Pat.)	9/FEB/2001	Yes

I hereby claim the benefit under 35 U.S.C. § 120 of any United States application(s), or § 365(c) of any PCT international application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT international application in the manner provided by the first paragraph of 35 U.S.C. § 112, I acknowledge the duty to disclose information which is material to patentability as defined in 37 C.F.R. § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

<u>Application No.</u>	<u>Filed (Day/Mo./Yr.)</u>	<u>(Patented, Pending, Abandoned)</u> <sup>Status</sup>
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I hereby appoint the practitioners associated with the firm and Customer Number provided below to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith, and direct that all correspondence be addressed to the address associated with that Customer Number:

**FITZPATRICK, CELLA, HARPER & SCINTO**

Customer Number: 05514

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that Such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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Full name of Sixth Inventor, if any \_\_\_\_\_  
Inventor's signature \_\_\_\_\_  
Date \_\_\_\_\_ Citizen/Subject of \_\_\_\_\_  
Residence \_\_\_\_\_  
Post Office Address \_\_\_\_\_

## Assignment

FOR VALUE RECEIVED

Akira UNNOTakao YONEHARATetsuro FUKUITakanori MATSUDAand Kiyotaka WASA

citizen(s) of Japan

residing at (respectively)

66-1-401 Ueki, Kamakura-shi, Kanagawa-ken, Japan;

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25-9 Tanacho, Aoba-ku, Yokohama-shi, Kanagawa-ken, Japan;

1-14-2-202 Shinishikawa, Aoba-ku, Yokohama-shi, Kanagawa-ken, Japan; and

2-7-27 Chiyogaoka, Nara-shi, Nara-ken, Japan

hereby sell, assign, transfer and convey unto

CANON KABUSHIKI KAISHA, a corporation of Japan having a place of business at  
3-30-2 Shimomaruko, Ohta-ku, Tokyo, Japan,

its successors, assigns and legal representatives (hereinafter called the "Assignee"), the entire right, title and interest, for the United States in and to certain inventions relating to

SEMICONDUCTOR SUBSTRATE, SOI SUBSTRATE AND MANUFACTURING METHOD THEREFOR

and described in an application for Letters Patent of the United States filed on 11/FEB/2002 as Application No. 10/068,988 and in and to said application, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues and extensions thereof; and we hereby authorize and request the Commissioner for Patents and Trademarks of the United States to issue all Letters Patent upon said inventions to the Assignee or to such nominees as it may designate.

AND we authorize and empower the said Assignee or nominees to invoke and claim for any application for patent or other form of protection for said inventions, the benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it, and to invoke and claim such right of priority without further written or oral authorization from us.

AND we hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any assignment, consent to file or like document which may be required in the United States for any purpose and more particularly in proof of the right of said Assignee or nominees to claim the aforesaid benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it.

AND we hereby covenant that we have the full right to convey the entire right, title and interest herein assigned and that we have not executed and will not execute any agreement in conflict herewith.

AND we hereby covenant and agree that we will communicate to said Assignee or nominees all facts known to us pertaining to said inventions, and testify in all legal proceedings, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and declarations and in general perform all lawful acts necessary or proper to aid said Assignee or nominees in obtaining, maintaining and enforcing all lawful patent protection for said inventions in the United States.

By: Akira Unno  
Akira UNNO

Date: May 17, 2002

By: Takao Yonehara  
Takao YONEHARA

Date: May 14, 2002

By: Tetsuro Fukui  
Tetsuro FUKUI

Date: May 14, 2002

By: Takanori Matsuda  
Takanori MATSUDA

Date: May 14, 2002

By: Kiyotaka Wasa  
Kiyotaka WASA

Date: May 23, 2002